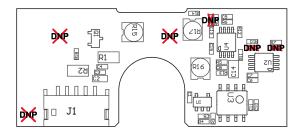
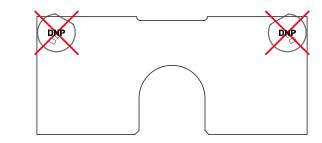
- ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZZ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: ISE4043	REV: E2	SUN REU: 1	Not In VersionControl
	TID #: TIDA-00378			
PLOT NAME = Top Assembly Drawing	GENERATED : 12/1/2	015 3: 43: 39	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: ISE4043	REV: E2	SUN REV: No	ot In VersionControl	
	TID #: TIDA-00378				
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/1/2	015 3: 43: 40	PM	TEXAS INSTRUMENTS	

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